



AO3420

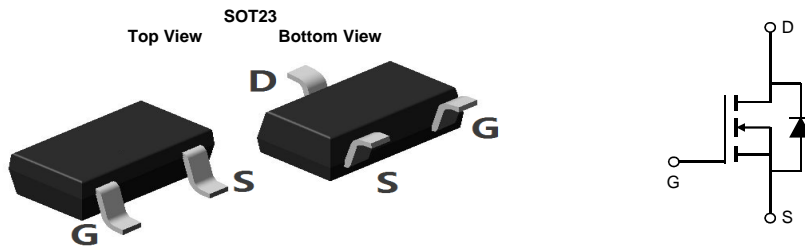
20V N-Channel MOSFET

General Description

The AO3420 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 1.8V while retaining a 12V $V_{GS(MAX)}$ rating. This device is suitable for use as a uni-directional or bi-directional load switch.

Product Summary

V_{DS}	20V
I_D (at $V_{GS}=10V$)	6A
$R_{DS(ON)}$ (at $V_{GS}=10V$)	< 24m Ω
$R_{DS(ON)}$ (at $V_{GS}=4.5V$)	< 27m Ω
$R_{DS(ON)}$ (at $V_{GS}=2.5V$)	< 42m Ω
$R_{DS(ON)}$ (at $V_{GS}=1.8V$)	< 55m Ω



Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	20	V
Gate-Source Voltage	V_{GS}	± 12	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	6
		$T_A=70^\circ\text{C}$	5
Pulsed Drain Current ^C	I_{DM}	30	A
Power Dissipation ^B	P_D	$T_A=25^\circ\text{C}$	1.4
		$T_A=70^\circ\text{C}$	0.9
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	70	90	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Ambient ^{A D}		100	125	$^\circ\text{C}/\text{W}$
Maximum Junction-to-Lead	$R_{\theta JL}$	63	80	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	20			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 12\text{V}$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	0.4	0.75	1.1	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=6\text{A}$ $T_J=125^\circ\text{C}$		16 23	24 35	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}$, $I_D=5\text{A}$		18	27	$\text{m}\Omega$
		$V_{GS}=2.5\text{V}$, $I_D=4\text{A}$		23	42	$\text{m}\Omega$
		$V_{GS}=1.8\text{V}$, $I_D=2\text{A}$		31	55	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=6\text{A}$		25		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$, $V_{GS}=0\text{V}$		0.7	1	V
I_S	Maximum Body-Diode Continuous Current				2	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=10\text{V}$, $f=1\text{MHz}$	420	525	630	pF
C_{oss}	Output Capacitance		65	95	125	pF
C_{rss}	Reverse Transfer Capacitance		45	75	105	pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$	0.8	1.7	2.6	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}$, $V_{DS}=10\text{V}$, $I_D=6\text{A}$		12.5		nC
$Q_g(4.5\text{V})$	Total Gate Charge			6		nC
Q_{gs}	Gate Source Charge			1		nC
Q_{gd}	Gate Drain Charge			2		nC
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=10\text{V}$, $V_{DS}=10\text{V}$, $R_L=1.7\Omega$, $R_{GEN}=3\Omega$		3		ns
t_r	Turn-On Rise Time			7.5		ns
$t_{D(off)}$	Turn-Off DelayTime			20		ns
t_f	Turn-Off Fall Time			6		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=6\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		14		ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=6\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		6		nC

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

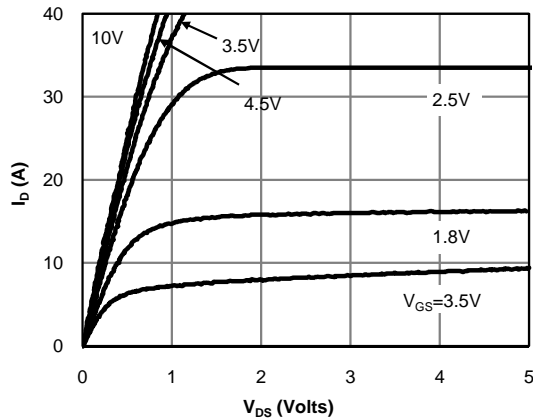


Fig 1: On-Region Characteristics (Note E)

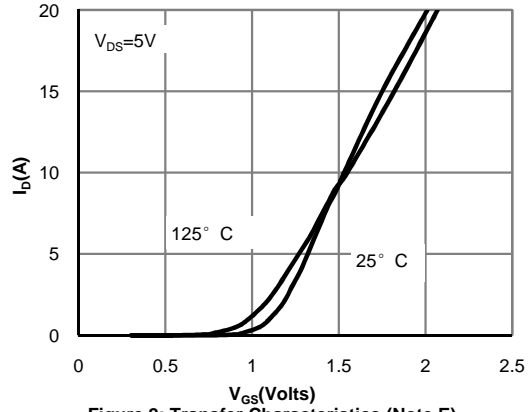


Figure 2: Transfer Characteristics (Note E)

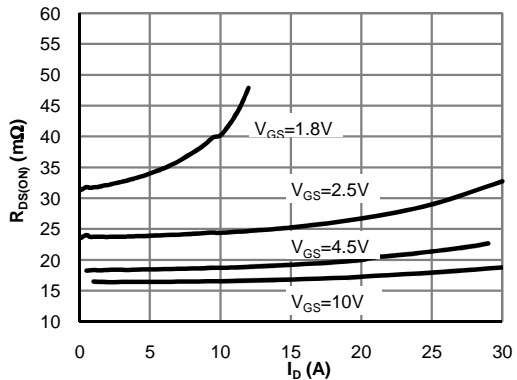


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

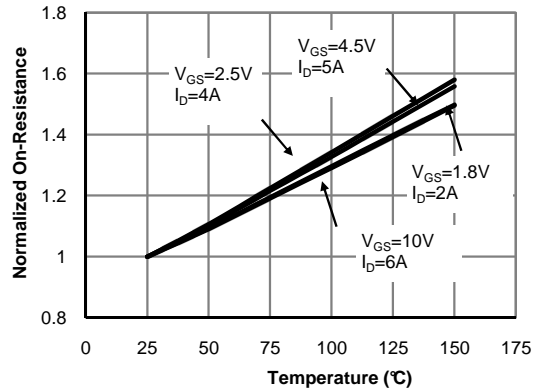


Figure 4: On-Resistance vs. Junction Temperature (Note E)

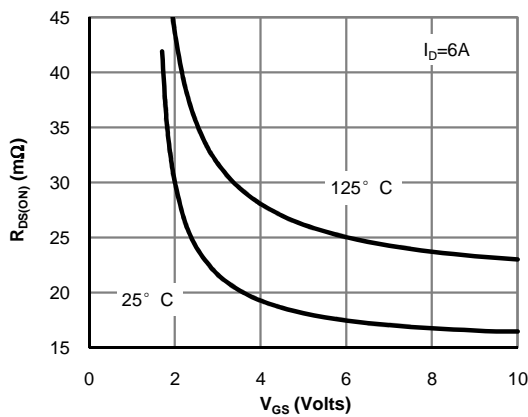


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

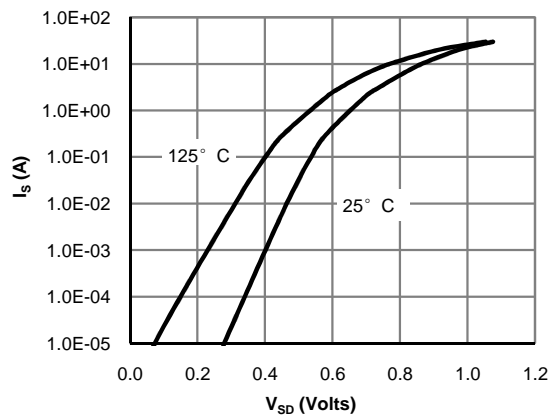


Figure 6: Body-Diode Characteristics (Note E)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

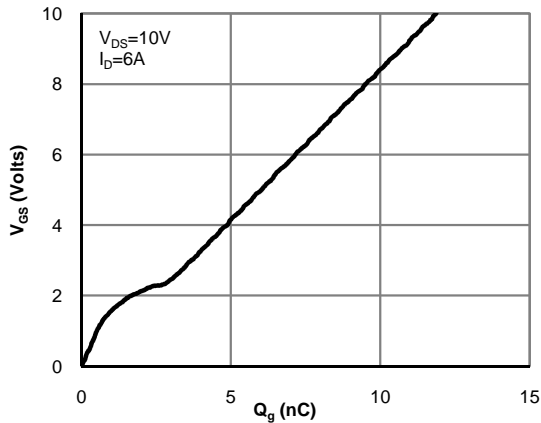


Figure 7: Gate-Charge Characteristics

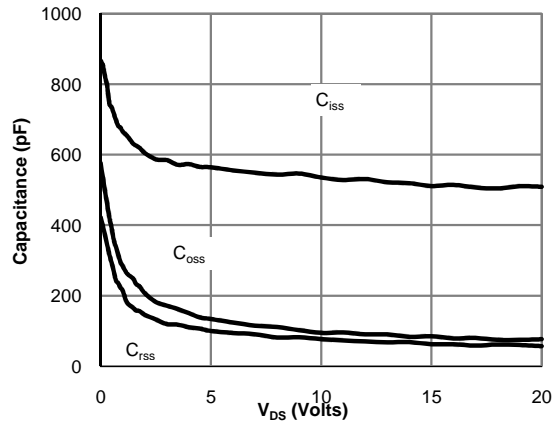


Figure 8: Capacitance Characteristics

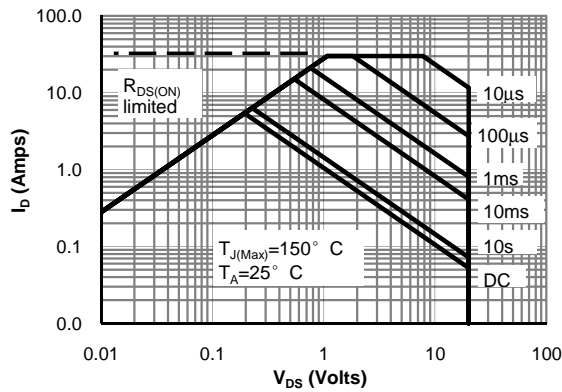


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

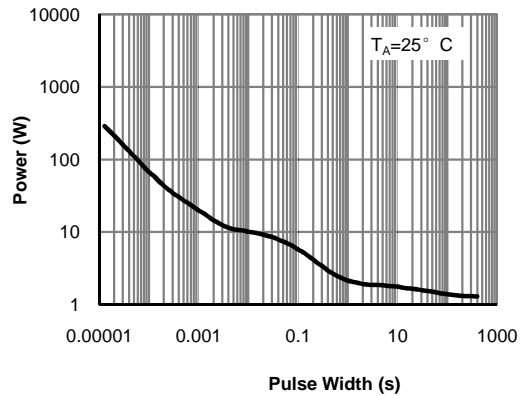


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

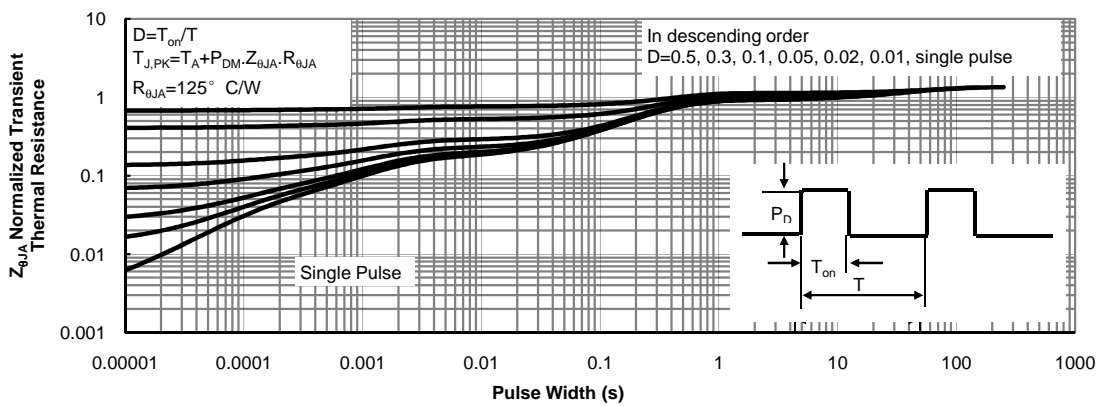
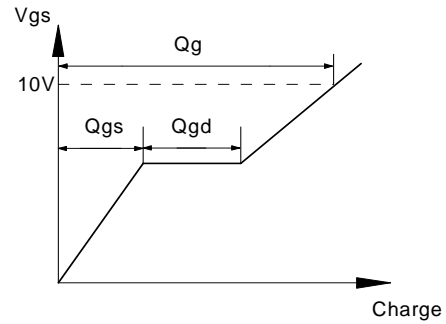
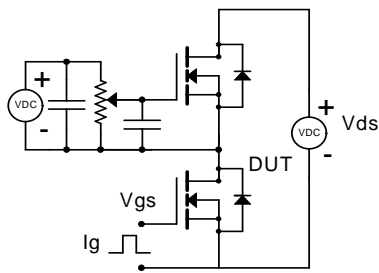
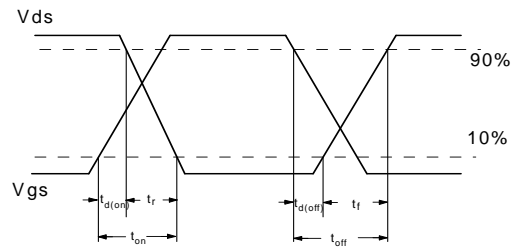
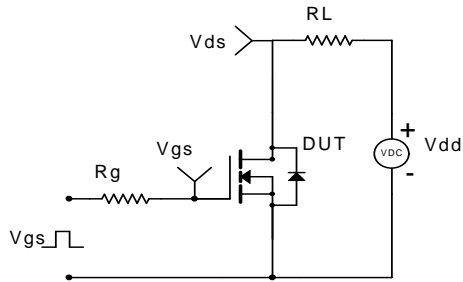


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms

